

IN THE SPECIFICATION

Please amend the specification as follows:

Replace the paragraph spanning pages 7-8, between page 7, line 33, and page 8, line 11 of the specification with the following:

In a further variant of the method of manufacturing described above of the module 10 according to the invention, a change takes place in the stage represented in Fig. 7. Instead of bonding the first stack S1 to the ~~second stack S~~ stack S2, the second stack S2 is bonded to a rubber film and diced into sections whereby each section can be used in a single module 10. With the aid of a so-called pick-and-place machine, the individual sections of the second stack S2 are then removed from the rubber film, dipped in the bonding agent and - after alignment - bonded to the first stack S1, each at the location of a single module 10. In the stage shown in Fig. 9, the grooves 8A of the second stack S2 have already been formed for the dicing operation and only the grooves 8B are formed in the first stack S1 during the dicing operation in order to

manufacture the individual modules 10. The assembly can then continue as described in Fig. 10 and as described during the discussion of the first example. It should be noted that the film 80 shown in Figs. 9 and 10 is adjacent to the first stack S1 which is deposited thereon with its upper surface.